

ABSTRACT

There is a laminate including:
a semiconductor substrate;
a support substrate that is light-transmissive; and
an adhesive layer and a release layer provided between
the semiconductor substrate and the support substrate,
the laminate being used when the release layer absorbs
light irradiated from a side of the support substrate and
then the semiconductor substrate and the support substrate
are separated from each other, wherein
the release layer is formed from a release agent
composition,
the release agent composition contains a light-
absorbing compound having a molecular weight of 2,000 or
less, and
when the light-absorbing compound is measured for an
absorption spectrum in a range of 250 to 800 nm, the
absorption spectrum has a local maximum value, which is a
maximum absorbance in a range of 250 to 800 nm, between 250
nm and 350 nm.

FIG. 1